PCN Number:		20160609002						Ρ	PCN Date:		06/13/2	016	
Title: Qualification of DMOS6 for LP8758A1B0YFFR													
Customer Contact:		P	CN I	Manager		D)ep	t:		Ouali	ty Servic	es	
Proposed 1 st Ship Date:				3/2016	Estimated Sample Availability:				Dat	Date provided at sample request.			
Change Type:													
Assembly Site				Assembly P	rocess				Assembly Materials				
Design				Electrical Specification							nical Specification		
Test Site					ipping/Labeling				Test Process				
Wafer Bump Site			<u>Ц</u>	Wafer Bum							p Proces	S	
Wafer Fab Sit	te		<u> </u>	Wafer Fab					Wafer Fab Process				
				Part number change									
				PCN	Details								
Description of C	hange:												
Texas Instruments is pleased to announce the qualification of its DMOS6 fabrication facility as an additional wafer FAB source for LP8758A1B0YFFR.													
C	Current S	Sites				Additi	ona	al S	Sites				
Current Fab Site				Wafer Diameter	Additional Fab Site	Pr	Process				Wafer Diameter		
RFAB	RFAB LBC8L\			300 mm	DMOS6	DMOS6 LBC8LV				300 mm			
Qual details are provided in the Qual Data Section.													
Reason for Chan	nge:												
Continuity of Supp													
Anticipated imp	act on l	Form,	Fit	, Function,	Quality or R	eliabil	lity	(p	ositiv	e / ne	egative)	:	
None													
Changes to prod	luct ide	entific	atio	on resulting	from this P	CN:							
Current													
Chip Sites		Chip Site Origin Code (20L)			Code (21L)				Chip Site City				
RFAB		RFB			USA			Richardson					
New Chip Site		Chip		e Origin Code 20L)	Chip Site Country Code (21L)				Chip Site		te City		
DMOS6				DM6	USA			D		Dall	las		
Sample product shipping label (not actual product label)													
MADE IN: Malaysia (Q) 2000 (D) 0336 20: 20: (Q) 2000 (D) 0336 MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 (Q) 2000 (D) 0336 MSL 1 /235C/UNLIM 03/29/04 (Q) 2000 (D) 0336													
ORT (P)													
LBL: 5A (L)TO:	1750		1	(20L) CSO: (22L) ASO:	SHE (21L) CC0:US/ HLA (23L) AC0: HY								
Product Affected:													
LP8758A1B0YFFR													

Qualification Report

LP8758 (Valdemar A1) Product Transfer to DMOS6 Qualification - LBC8LV process at DMOS6 / Assembled in a 35 bump, 0.4mm BOP-COA WCSP in Clark Approved 06/08/2016

Product Attributes

Attributes	Qual Device: LP8758A1B0YFFR
Assembly Site	CLARK AT
Package Family	DSBGA
Wafer Fab Site	DM0S6
Wafer Fab Process	LBC8LV

- QBS: Qual By Similarity - Qual Device LP8758A1B0YFFR is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LP8758A1B0YFFR
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	3/225/0
AC	Autoclave 121C	96 Hours	3/231/0
TC	Temperature Cycle, -55/125C	700 Cycles	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0
HBM	ESD - HBM	2500 V	3/9/0
CDM	ESD - CDM	1500 V	3/9/0
LU	Latch-up	(per JESD78) 25C	3/18/0
LU	Latch-up	(per JESD78) 85C	3/18/0
LU	Latch-up	(per JESD78) 125C	3/18/0
ED	Electrical Characterization	Per Datasheet Parameters	3/Pass
MQ	Manufacturability (Assembly)	(per mfg site specification)	Pass
MQ	Manufacturability (Fab)	(per mfg site specification)	Pass
WLR	Wafer Level Reliability	(per mfg site specification)	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and

155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com